

NS7520 Material Composition

Component	Weight	Material		Weight	Weight
	[mg]	CAS No.	Name	[mg]	
Chip	12.40	7440-21-3	Si	12.40	3.13
Frame	96.40	65997-17-3	Glass crossing	13.70	3.46
		7440-50-8	Cu	48.80	12.31
		7440-02-0	Ni	2.60	0.66
		7440-57-5	Au	0.30	0.08
			Thermosetting Resin	10.60	2.67
			Additive agent ,other	20.40	5.15
Bonding wire	4.20	7440-57-5	Au	4.20	1.06
Die attach	1.10	14808-60-7		0.50	0.13
			Epoxy,other	0.60	0.15
Epoxy Resin	197.00	60676-86-0	Silica(SiO2)	161.50	40.73
			Epoxy,other	17.70	4.46
		106466-55-1	Phenol Resin	9.40	2.37
		1309-64-4	Antiminous Trioxide	3.90	0.98
		68541-56-0	Bromide Compounds	4.50	1.13
Solder ball	85.40	7440-31-5	Sn	82.40	20.78
		7440-22-4	Ag	2.60	0.66
		7440-50-8	Cu	0.40	0.10
Total Weight	396.50				